

US 20240237280A9

## (19) United States

# (12) Patent Application Publication LIANG et al.

## (10) Pub. No.: US 2024/0237280 A9

# (48) **Pub. Date: Jul. 11, 2024 CORRECTED PUBLICATION**

## (54) SYSTEMS FOR THERMAL MANAGEMENT OF AN ELECTRONIC DEVICE

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- (21) Appl. No.: 18/047,860
- (22) Filed: Oct. 19, 2022

### **Prior Publication Data**

- (15) Correction of US 2024/0138107 A1 Apr. 25, 2024 See (22) Filed.
- (65) US 2024/0138107 A1 Apr. 25, 2024

### **Publication Classification**

(51) Int. Cl. *H05K 7/20* (2006.01) *H05K 1/02* (2006.01)

(52) **U.S. CI.** CPC ...... *H05K 7/20272* (2013.01); *H05K 1/0201* (2013.01)

### (57) ABSTRACT

Systems are provided for a cooling system for an electric device. In one example, a system includes a metallic plate coupled to a circuit board and a coolant manifold. The coolant manifold comprises a semi-open coolant channel configured to flow coolant in contact with the metallic plate.



